

Thermal transfer compound and thermal interface film

Silicon thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.



art. no.	container	delivery quantity [g]
WLP 004	box	4
WLP 035	box	35
WLP 500	box	500
WLP 300 S	cartridge	300
WLP 500 S	cartridge	500

Silicone-free thermal transfer compound

Thermal transfer compound used to reduce the thermal transmission resistance between semiconductor and heatsink.



art. no.	container	delivery quantity [ml]
WLPF 05	syringe	2
WLPF 10	syringe	5
WLPF 20	syringe	10
WLPF 50	syringe	20

Technical data

	WLP	WLPF
composition	silicone oil, inorganic filling material	Silicone free synthetic liquid. Metal oxide filling.
consistance	pastey	pastey
colour	white	white-grey
tightness	1.1 g/cm ³	ca. 2 g/cm ³
thermal conductivity	0.61	>0.7
specific electrical resistance	>10 ¹² Ω/cm	>10 ¹² Ω/cm
flashpoint	none (DIN 53213)	of the basic oil >280 °C (ISO 2592)
drop point	>260 °C	–
thermal resistance	no bleeding at (4 h / 200°C)	<1 % (96 h / 200 °C)
temper. range	-70 °C ... +250 °C	-40 °C ... +150 °C
acid number	< 0.01 mg KOH/g	–
solubility in water	insoluble	insoluble

E 13	Mica wafers	→ E 11	Silicone wafers	→ E 2 – 4
	Kapton insulator washers	→ E 8	Thermal conductive foil	→ E 5
	Mounting pads	→ E 37	Thermal. conductive silicone foam foil	→ E 6
	Mounting parts for heatsinks	→ E 40 – 41	Insulator caps	→ E 41